The 13th International Workshop on Microelectronics Assembling and Packaging

Program Overview

Date: 7th November, 2013/ Venue: Takakura Hotel, Fukuoka		
10:20 ~ 10:30	Opening Remark	Poster Exhibition
10:30 ~ 12:30	Session 1: Invited Talks	
12:30 ~ 13:30	Lunch Break	
13:30 ~ 15:10	Session 2: Packaging Supply Chain	
15:10 ~ 15:30	Break	
15:30 ~ 17:10	Session 3: 3D Integration Technology	
17:10 ~ 17:30	Break	
17:30 ~ 18:20	Session 4: Vietnam Session	
18:30 ~ 20:00	Session 5: Poster Session (Reception Party)	

MAP2013 Program

Thursday 7th, November

10:20~10:30 Opening Remark

Hajime Tomokage
Fukuoka University(JAPAN)

10:30~12:30 Session 1: Invited Talks

Chair: Kiyoshi Arita
Panasonic Factory Solutions Co., Ltd.(JAPAN)

10:30-11:10 1-1 Research & development of semiconductor devices for space applications
Hiroyuki Shindo
Japan Aerospace Exploration Agency (JAPAN)

11:10-11:50 1-2 3D packaging technology enabling next generation devices
Mark Gerber
Texas Instruments Incorporated (U.S.A.)

11:50-12:30 1-3 Embedded and stacking technology in ITRI (tentative)
Wei-Chung Lo
Industrial Technology Research Institute (TAIWAN)

12:30 ~ 13:30 Lunch Break

13:30~15:10 Session 2: Packaging Supply Chain

Chair: Hisao Kasuga
International Standardization – Innovation Technology Research Association (INOTEK) (JAPAN)

13:30-13:50 2-1 LSI turnkey network business
Hiroyuki Kataoka
Hibikino System-Lab Inc. (JAPAN)

13:50-14:10 2-2 Cu balls and Cu-core balls for 3D packaging
Hiroyoshi Kawasaki
Senju Metal Indudtry Co., Ltd. (JAPAN)

14:10-14:30 2-3 Proposing “high current handling PCB”, an effective solution for heat countermeasure of semiconductor -introduction to advanced technology supporting emerging power semiconductors-
Manabu Mizuo
TAIYO KOGYO CO., LTD.

14:30-14:50 2-4 SAMURAI CSP provider
Jake Shibata
Tera Probe, lnc. (JAPAN)

14:50-15:10 2-5 On achieving capture power safety in at-speed scan-based logic BIST
Akihiro Tomita
Kyushu Institute of Technology(JAPAN)

15:10-15:30 Break

15:30-17:10 Session 3: 3D Integration Technology

Chair: Hajime Tomokage
Fukuoka University(JAPAN)

15:30-15:50 3-1 Updated status on embedding device technology in international standardization (IEC/TC91: electronics assembly)
Hisao Kasuga
International Standardization – Innovation Technology Research Association (INOTEK) (JAPAN)

15:50-16:10 3-2 The technology of CR-8000 for device embedded substrate
Hirohiko Matsuzawa
Zuken Inc. (JAPAN)

16:10-16:30 3-3 Parts mounting system for manufacturing PCBs with embedded components using FUJIKO
Hiroyuki Ao
Fuji Machine Mfg. Co., Ltd.(JAPAN)

16:30-16:50 3-4 T Through Silicon Via Process Using DRIE and Cathode PE-CVD
Tomoyuki Nonaka
SAMCO Inc. (JAPAN)

16:50-17:10 3-5 High thermal conductive inter chip fill for 3D-IC through pre-applied joining
Yasuhiro Kawase
Mitsubishi Chemical Corporation (JAPAN)

17:10-17:30 Break

17:30-18:20 Session 4: Vietnam Session

Chair: Daisuke Yoshimitsu
SangyoTimes Inc.(JAPAN)

17:30-18:00 4-1 Introduction to the program “Development of integrated circuit industry of Ho Chi Minh City (tentative)
Hoang Ngo Duc
Vietnam National University Integrated Circuit Design Research and Education Center (Vietnam)

18:00-18:20 4-2 Collaboration between Vietnam national university with Kyushu institute of technology in terms of semiconductor fabrication and Wi-Fi chip design
Hiroshi Ochi
Kyushu Institute of Technology (JAPAN)

18:30~20:00 Poster session; Reception Party

5-1	DENKEN Co., Ltd.	5-2	ALPHA DESIGN Co., Ltd.
5-3	Hibikino System-Lab Inc.	5-4	SAGA ELECTRONICS Co., Ltd.
5-5	FUKUDEN SHIZAI K.K.	5-6	Keirex Technology Inc.
5-7	YDC Corporation	5-8	Zuken Inc.
5-9	FUJI MACHINE MFG. Co., Ltd.	5-10	Noda Screen Co., Ltd.
5-11	WALTS Co., Ltd.	5-12	Hitachi Chemical Co., Ltd.
5-13	Senju Metal Industry Co., Ltd.	5-14	TAIYO KOGYO Corporation
5-15	SAMCO Inc.	5-16	PMT CORPORATION
5-17	Tera Probe, lnc.	5-18	OMRON Corporation
5-19	Kyushu Institute of Technology	5-20	Ellia Co., Ltd.

MAP2013 参加申込用紙

必要事項をご記入の上、アジア半導体機構事務局（担当：古賀）、FAX(092-721-4904)へファックスもしくはE-mail(astsa@kerc.or.jp)でお送り下さい。折り返し、ご請求書をお送りします

氏名 ____________________

会社名 ____________________

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住所　〒 ____________________

E-mail ____________________

電話 ____________________ Fax ____________________

ご不明な点ございましたら、下記まで御連絡下さい。

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Fax: 092-721-4904　E-mail: astsa@kerc.or.jp

---開催場所にご注意下さい---

開催場所が変更となりましたので、ご注意下さい。

MAP2013

会期:2013 年 11 月 7 日(木) 10:20～18:00

会場:タカクラホテル福岡

福岡市中央区渡辺通 2-7-21

最寄り駅:福岡市市営地下鉄 渡辺通駅 徒歩 5 分

西鉄薬院駅 徒歩 5 分

Google Map

---お問い合わせ先---

MAP2013

MAP2013 実行委員会事務局(財団法人九州経済調査協会内)

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